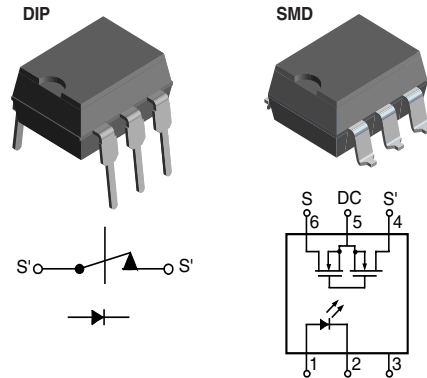


1 Form B Solid State Relay

Features

- Isolation Test Voltage 3750 V_{RMS}
- Typical R_{ON} 10 Ω
- Load Voltage 200 V
- Clean Bounce Free Switching
- Low Power Consumption
- SMD Lead Available on Tape and Reel
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



Agency Approvals

- UL1577, File No. E52744 System Code H or J, Double Protection
- CSA - Certification 093751

Applications

- General Telecom Switching
- Security Equipment
- Instrumentation
- Industrial Controls

Description

The LH1511 relays are SPST normally closed switches (1 Form B) that can replace electromechanical relays in many applications. The relays are constructed as a multi-chip hybrid device. Actuation control is via an Infrared LED. The output switch is a combination of a photodiode array with MOSFET switches and control circuitry. The relays can be configured for AC/DC or DC only operation.

Order Information

| Part | Remarks |
|-------------|--------------------------------|
| LH1511BAB | Gullwing, Tubes, SMD-6 |
| LH1511BABTR | Gullwing, Tape and Reel, SMD-6 |
| LH1511BT | Tubes, DIP-6 |

Absolute Maximum Ratings, T_{amb} = 25 °C

Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Ratings for extended periods of time can adversely affect reliability.

SSR

| Parameter | Test condition | Symbol | Value | Unit |
|--|------------------------|----------------|-------|------|
| LED continuous forward current | | I _F | 50 | mA |
| LED reverse voltage | I _R ≤ 10 μA | V _R | 8.0 | V |
| DC or peak AC load voltage | I _L ≤ 50 μA | V _L | 200 | V |
| Continuous DC load current - bidirectional operation | | I _L | 200 | mA |

| Parameter | Test condition | Symbol | Value | Unit |
|---|---|------------|---------------|-----------|
| Continuous DC load current - unidirectional operation | | I_L | 300 | mA |
| Peak load current (single shot) | $t = 100 \text{ ms}$ | I_P | 400 | mA |
| Ambient temperature range | | T_{amb} | - 40 to + 85 | °C |
| Storage temperature range | | T_{stg} | - 40 to + 125 | °C |
| Pin soldering temperature | $t = 10 \text{ s max}$ | T_{sld} | 260 | °C |
| Input/output isolation voltage | $V_{RMS} t = 1.0 \text{ s}, I_{ISO} = 10 \mu\text{A max}$ | V_{ISO} | 3750 | V_{RMS} |
| Output power dissipation (continuous) | | P_{diss} | 550 | mW |

Electrical Characteristics, $T_{amb} = 25 \text{ °C}$

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements.

Input

| Parameter | Test condition | Symbol | Min | Typ. | Max | Unit |
|--------------------------------------|---|------------|------|------|------|------|
| LED forward current, switch turn-on | $I_L = \pm 200 \text{ mA}, t = 10 \text{ ms}$ | I_{Fon} | 0.2 | 0.9 | | mA |
| LED forward current, switch turn-off | $V_L = \pm 150 \text{ V}$ | I_{Foff} | | 1.0 | 2.0 | mA |
| LED forward voltage | $I_F = 10 \text{ mA}$ | V_F | 1.15 | 1.26 | 1.45 | V |

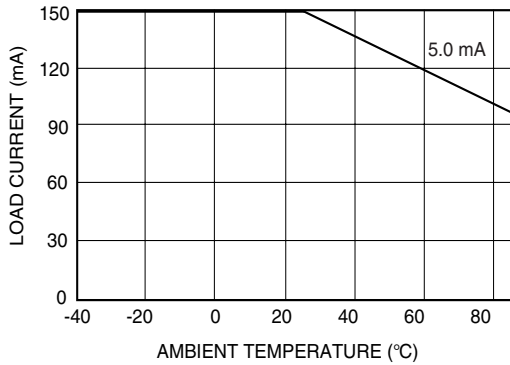
Output

| Parameter | Test condition | Symbol | Min | Typ. | Max | Unit |
|--|---|-----------|-----|------|------|---------------|
| ON-resistance ac/dc : Pin 4, 6 (+) to 5 (-) | $I_F = 0 \text{ mA}, I_L = 50 \text{ mA}$ | R_{ON} | | 10 | 15 | Ω |
| ON-resistance dc: Pin 4, 6 (+) to 5 (-) | $I_F = 0 \text{ mA}, I_L = 100 \text{ mA}$ | R_{ON} | | 2.5 | 3.75 | Ω |
| Off-resistance | $I_F = 5.0 \text{ mA}, V_L = \pm 100 \text{ V}$ | R_{OFF} | 0.1 | 1.4 | | $G\Omega$ |
| Off-state leakage current | $I_F = 5.0 \text{ mA}, V_L = \pm 200 \text{ V}$ | I_O | | 0.07 | 1.0 | μA |
| Output capacitance | $I_F = 5.0 \text{ mA}, V_L = 50 \text{ V}$ | C_O | | 50 | | pf |

Transfer

| Parameter | Test condition | Symbol | Min | Typ. | Max | Unit |
|----------------------------|--|-----------|-----|------|-----|------|
| Capacitance (input-output) | $V_{ISO} = 1.0 \text{ V}$ | C_{IO} | | 3.0 | | pF |
| Turn-on time | $I_F = 10 \text{ mA}, I_L = 50 \text{ mA}$ | t_{on} | | 1.2 | 3.0 | ms |
| Turn-off time | $I_F = 10 \text{ mA}, I_L = 50 \text{ mA}$ | t_{off} | | 1.0 | 3.0 | ms |

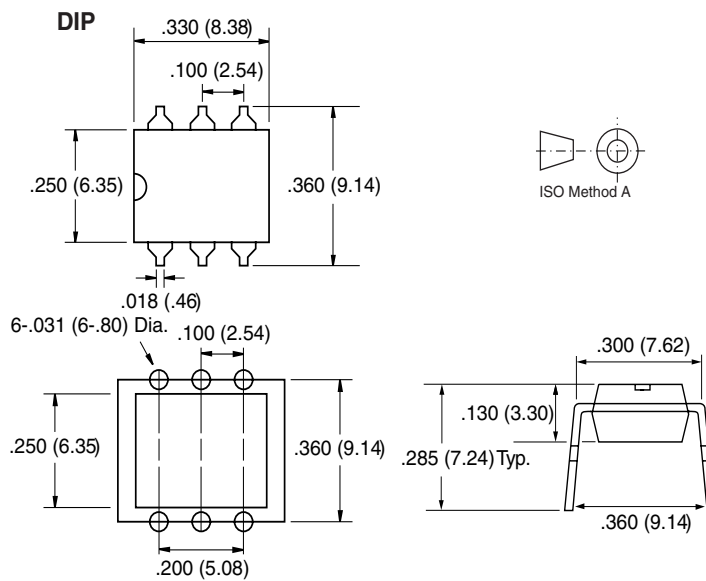
Typical Characteristics (Tamb = 25 °C unless otherwise specified)



lh1511bt_00

Figure 1. Recommended Operating Conditions

Package Dimensions in Inches (mm)



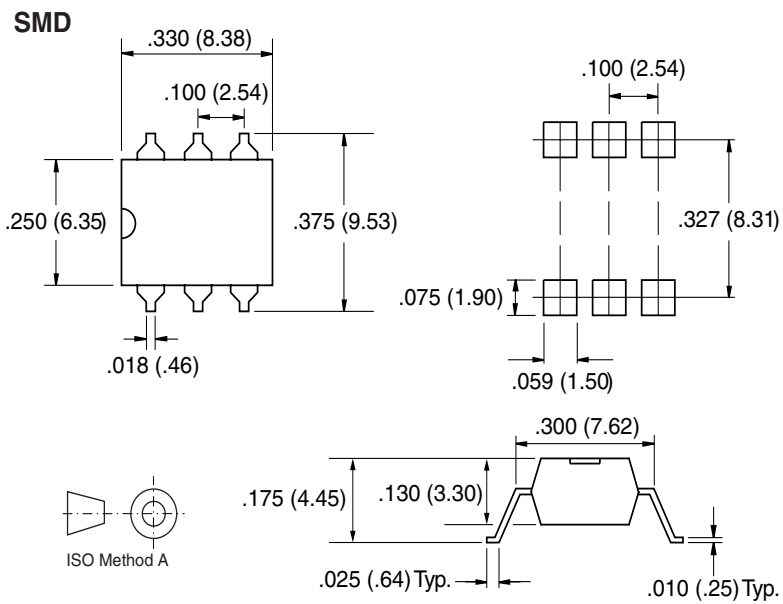
i178015

LH1511BAB/ BABTR/ BT



Vishay Semiconductors

Package Dimensions in Inches (mm)



i178016



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

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